National Semiconductor

July 1999

# LM341/LM78MXX Series 3-Terminal Positive Voltage Regulators

### **General Description**

The LM341 and LM78MXX series of three-terminal positive voltage regulators employ built-in current limiting, thermal shutdown, and safe-operating area protection which makes them virtually immune to damage from output overloads.

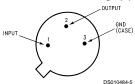
With adequate heatsinking, they can deliver in excess of 0.5A output current. Typical applications would include local (on-card) regulators which can eliminate the noise and degraded performance associated with single-point regulation.

### **Features**

- Output current in excess of 0.5A
- No external components
- Internal thermal overload protection
- Internal short circuit current-limiting
- Output transistor safe-area compensation
- Available in TO-220, TO-39, and TO-252 D-PAK packages
- Output voltages of 5V, 12V, and 15V

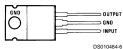
## **Connection Diagrams**

### TO-39 Metal Can Package (H)



**Bottom View** Order Number LM78M05CH, LM78M12CH or LM78M15CH See NS Package Number H03A

### TO-220 Power Package (T)



### **Top View**

Order Number LM341T-5.0, LM341T-12, LM341T-15, LM78M05CT, LM78M12CT or LM78M15CT See NS Package Number T03B



**Top View** Order Number LM78M05CDT See NS Package Number TD03B

# **Absolute Maximum Ratings** (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Lead Temperature (Soldering, 10 seconds)

TO-39 Package (H) 300°C TO-220 Package (T) 260°C

Storage Temperature Range Operating Junction Temperature Range

–40°C to +125°C

 $-65^{\circ}\text{C}$  to  $+150^{\circ}\text{C}$ 

Power Dissipation (Note 2) Internally Limited Input Voltage

 $5V \le V_O \le 15V$ 35V ESD Susceptibility TBD

## **Electrical Characteristics**

Limits in standard typeface are for  $T_J = 25^{\circ}C$ , and limits in **boldface type** apply over the  $-40^{\circ}C$  to  $+125^{\circ}C$  operating temperature range. Limits are guaranteed by production testing or correlation techniques using standard Statistical Quality Control (SQC)

## LM341-5.0, LM78M05C

Unless otherwise specified:  $V_{IN}$  = 10V,  $C_{IN}$  = 0.33  $\mu$ F,  $C_{O}$  = 0.1  $\mu$ F

Symbol	Parameter	Conditions	Min	Тур	Max	Units
Vo	Output Voltage	I <sub>L</sub> = 500 mA	4.8	5.0	5.2	V
		5 mA ≤ I <sub>L</sub> ≤ 500 mA	4.75	5.0	5.25	
		$P_D \le 7.5W, 7.5V \le V_{IN} \le 20V$				
V <sub>R LINE</sub>	Line Regulation	$7.2V \le V_{IN} \le 25V$			50	mV
		I <sub>L</sub> = 500 mA			100	
V <sub>R LOAD</sub>	Load Regulation	5 mA ≤ I <sub>L</sub> ≤ 500 mA			100	
Ι <sub>Q</sub>	Quiescent Current	I <sub>L</sub> = 500 mA		4	10.0	mA
$\Delta I_Q$	Quiescent Current Change	5 mA ≤ I <sub>L</sub> ≤ 500 mA			0.5	
		$7.5V \le V_{IN} \le 25V$ , $I_{L} = 500 \text{ mA}$			1.0	
V <sub>n</sub>	Output Noise Voltage	f = 10 Hz to 100 kHz		40		μV
$\Delta V_{IN}$	Ripple Rejection	f = 120 Hz, I <sub>L</sub> = 500 mA		78		dB
$\Delta V_{O}$				'6		ub ub
V <sub>IN</sub>	Input Voltage Required	I <sub>L</sub> = 500 mA	7.2			V
	to Maintain Line Regulation					
ΔV <sub>O</sub>	Long Term Stability	I <sub>L</sub> = 500 mA			20	mV/khrs

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### **Electrical Characteristics**

Limits in standard typeface are for  $T_J$  = 25°C, and limits in **boldface type** apply over the -40°C to +125°C operating temperature range. Limits are guaranteed by production testing or correlation techniques using standard Statistical Quality Control (SQC) methods. (Continued)

## LM341-12, LM78M12C

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Unless otherwise specified:  $V_{IN}$  = 19V,  $C_{IN}$  = 0.33  $\mu F$ ,  $C_{O}$  = 0.1  $\mu F$ 

Symbol	Parameter	Conditions		Min	Тур	Max	Units
Vo	Output Voltage I <sub>L</sub> = 500 mA			11.5	12	12.5	V
		$5 \text{ mA} \le I_L \le 500 \text{ mA}$ $P_D \le 7.5W, 14.8V \le V_{IN} \le 27V$		11.4	12	12.6	
V <sub>R LINE</sub>	Line Regulation	14.5V ≤ V <sub>IN</sub> ≤ 30V	I <sub>L</sub> = 100 mA			120	mV
			I <sub>L</sub> = 500 mA			240	
V <sub>R LOAD</sub>	Load Regulation	5 mA ≤ I <sub>L</sub> ≤ 500 mA	5 mA ≤ I <sub>L</sub> ≤ 500 mA			240	
IQ	Quiescent Current	I <sub>L</sub> = 500 mA			4	10.0	mA
ΔI <sub>Q</sub> Quiescent Current Change		5 mA ≤ I <sub>L</sub> ≤ 500 mA				0.5	
		14.8V ≤ V <sub>IN</sub> ≤ 30V, I <sub>L</sub> = 5	500 mA			1.0	
V <sub>n</sub>	Output Noise Voltage	f = 10 Hz to 100 kHz			75		μV
$\frac{\Delta V_{IN}}{\Delta V_{O}}$	Ripple Rejection	f = 120 Hz, I <sub>L</sub> = 500 mA			71		dB
V <sub>IN</sub>	Input Voltage Required	I <sub>L</sub> = 500 mA		14.5			V
	to Maintain Line Regulation						
ΔVο	Long Term Stability	I <sub>L</sub> = 500 mA				48	mV/khrs

## LM341-15, LM78M15C

Unless otherwise specified:  $V_{IN}$  = 23V,  $C_{IN}$  = 0.33  $\mu$ F,  $C_{O}$  = 0.1  $\mu$ F

Symbol	Parameter	Conditions		Min	Тур	Max	Units
Vo	Output Voltage	I <sub>L</sub> = 500 mA		14.4	15	15.6	V
		5 mA ≤ I <sub>L</sub> ≤ 500 mA		14.25	15	15.75	
		$P_D \le 7.5W, 18V \le V_{IN} \le 30V$					
V <sub>R LINE</sub>	Line Regulation	17.6V ≤ V <sub>IN</sub> ≤ 30V	I <sub>L</sub> = 100 mA			150	mV
			I <sub>L</sub> = 500 mA			300	
V <sub>R LOAD</sub>	Load Regulation	5 mA ≤ I <sub>L</sub> ≤ 500 mA	5 mA ≤ I <sub>L</sub> ≤ 500 mA			300	
Iq	Quiescent Current	I <sub>L</sub> = 500 mA			4	10.0	mA
$\Delta I_Q$	Quiescent Current Change	5 mA ≤ I <sub>L</sub> ≤ 500 mA				0.5	
		18V ≤ V <sub>IN</sub> ≤ 30V, I <sub>L</sub> = 500 mA				1.0	
V <sub>n</sub>	Output Noise Voltage	f = 10 Hz to 100 kHz			90		μV
ΔV <sub>IN</sub>	Ripple Rejection	f = 120 Hz, I <sub>L</sub> = 500 mA					
$\Delta V_{O}$					69		dB
V <sub>IN</sub>	Input Voltage Required	I <sub>L</sub> = 500 mA		17.6			V
	to Maintain Line Regulation						
ΔV <sub>O</sub>	Long Term Stability	I <sub>L</sub> = 500 mA				60	mV/khrs

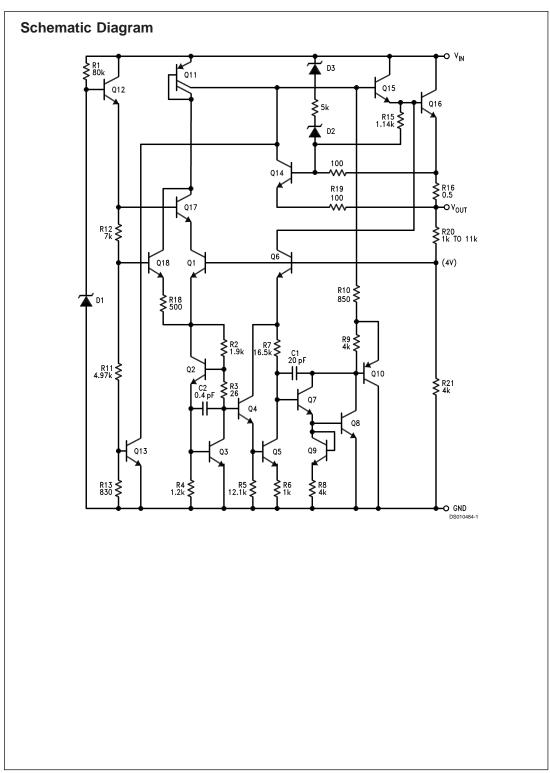
Note 1: Absolute maximum ratings indicate limits beyond which damage to the component may occur. Electrical specifications do not apply when operating the device outside of its rated operating conditions.

Note 2: The typical thermal resistance of the three package types is:

**T** (TO-220) package:  $\theta_{(JA)}$  = 60 °C/W,  $\theta_{(JC)}$  = 5 °C/W

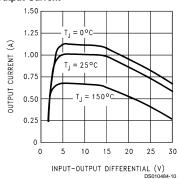
**H** (TO-39) package:  $\theta_{(JA)}$  = 120 °C/W,  $\theta_{(JC)}$  = 18 °C/W

**DT** (TO-252) package:  $\theta_{\rm (JA)}$  = 92 °C/W,  $\theta_{\rm (JC)}$  = 10 °C/W

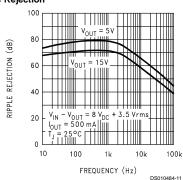


# **Typical Performance Characteristics**

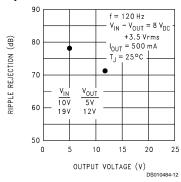
### **Peak Output Current**



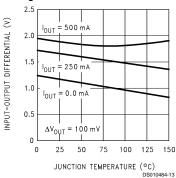
### Ripple Rejection



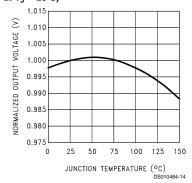
### Ripple Rejection



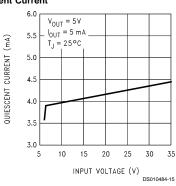
### **Dropout Voltage**



# Output Voltage (Normalized to 1V at $T_J = 25^{\circ}C$ )

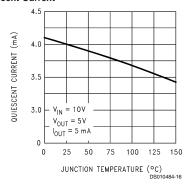


### **Quiescent Current**

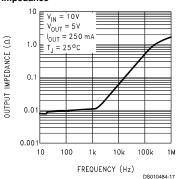


### **Typical Performance Characteristics** (Continued)

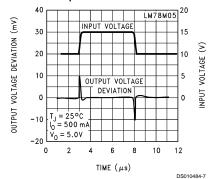
#### **Quiescent Current**



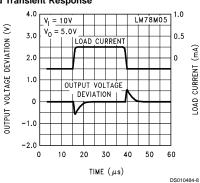
### **Output Impedance**



### Line Transient Response



### Load Transient Response



### **Design Considerations**

The LM78MXX/LM341XX fixed voltage regulator series has built-in thermal overload protection which prevents the device from being damaged due to excessive junction temperature

The regulators also contain internal short-circuit protection which limits the maximum output current, and safe-area protection for the pass transistor which reduces the short-circuit current as the voltage across the pass transistor is in-

Although the internal power dissipation is automatically limited, the maximum junction temperature of the device must be kept below +125°C in order to meet data sheet specifications. An adequate heatsink should be provided to assure this limit is not exceeded under worst-case operating conditions (maximum input voltage and load current) if reliable performance is to be obtained).

# ronment. Below is a list of variables that may affect the ther-R<sup>⊕JC</sup>(Component Variables) R<sup>⊕CA</sup>(Application Variables)

mal resistance and in turn the need for a heatsink.

device junction flows through the die to the die attach pad,

through the lead frame to the surrounding case material, to

the printed circuit board, and eventually to the ambient envi-

Leadframe Size & Material Mounting Pad Size, Material,

& Location

No. of Conduction Pins Placement of Mounting Pad

Die Size PCB Size & Material Die Attach Material Traces Length & Width Molding Compound Size and Adjacent Heat Sources

Material

6

Volume of Air Air Flow

Ambient Temperature Shape of Mounting Pad

## 1.0 Heatsink Considerations

When an integrated circuit operates with appreciable current, its junction temperature is elevated. It is important to quantify its thermal limits in order to achieve acceptable performance and reliability. This limit is determined by summing the individual parts consisting of a series of temperature rises from the semiconductor junction to the operating environment. A one-dimension steady-state model of conduction heat transfer is demonstrated in The heat generated at the

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## **Design Considerations** (Continued)

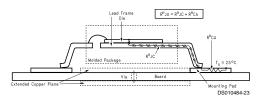


FIGURE 1. Cross-sectional view of Integrated Circuit Mounted on a printed circuit board. Note that the case temperature is measured at the point where the leads contact with the mounting pad surface

The LM78MXX/LM341XX regulators have internal thermal shutdown to protect the device from over-heating. Under all possible operating conditions, the junction temperature of the LM78MXX/LM341XX must be within the range of 0°C to 125°C. A heatsink may be required depending on the maximum power dissipation and maximum ambient temperature of the application. To determine if a heatsink is needed, the power dissipated by the regulator, P<sub>D</sub>, must be calculated:

$$I_{\rm IN} = I_{\rm L} + I_{\rm G}$$

$$\mathsf{P}_\mathsf{D} = (\mathsf{V}_\mathsf{IN} \!\!-\! \mathsf{V}_\mathsf{OUT}) \; \mathsf{I}_\mathsf{L} + \mathsf{V}_\mathsf{IN} \mathsf{I}_\mathsf{G}$$

shows the voltages and currents which are present in the circuit.

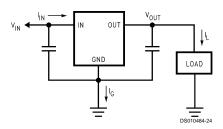


FIGURE 2. Power Dissipation Diagram

The next parameter which must be calculated is the maximum allowable temperature rise,  $T_{\rm R}({\rm max})$ :

$$\theta_{JA}$$
 = TR (max)/P<sub>D</sub>

If the maximum allowable value for  $\theta_{JA}$  °C/w is found to be  $\geq$ 60°C/W for TO-220 package or  $\geq$ 92°C/W for TO-252 package, no heatsink is needed since the package alone will dissipate enough heat to satisfy these requirements. If the calculated value for  $\theta_{JA}$  fall below these limits, a heatsink is required.

As a design aid, Table 1 shows the value of the  $\theta_{JA}$  of TO-252 for different heatsink area. The copper patterns that we used to measure these  $\theta_{JA}$  are shown at the end of the Application Note Section. reflects the same test results as what are in the Table 1

shows the maximum allowable power dissipation vs. ambient temperature for the TO-252 device. shows the maximum allowable power dissipation vs. copper area (in²) for the TO-252 device. Please see AN1028 for power enhancement techniques to be used with TO-252 package.

TABLE 1.  $\theta_{JA}$  Different Heatsink Area

TABLE 1. OJA BINGIGHT HEATSHIK AIGA						
Сорре	Thermal Resistance					
Top Sice (in <sup>2</sup> )*	Bottom Side (in <sup>2</sup> )	(θ <sub>JA</sub> , °C/W) TO-252				
0.0123	0	103				
0.066	0	87				
0.3	0	60				
0.53	0	54				
0.76	0	52				
1	0	47				
0	0.2	84				
0	0.4	70				
0	0.6	63				
0	0.8	57				
0	1	57				
0.066	0.066	89				
0.175	0.175	72				
0.284	0.284	61				
0.392	0.392	55				
0.5	0.5	53				
	Coppe Top Sice (in²)*  0.0123  0.066  0.3  0.53  0.76  1  0  0  0  0  0  0 0  0.066  0.175  0.284  0.392	Copper Area           Top Sice (in²)*         Bottom Side (in²)           0.0123         0           0.066         0           0.3         0           0.53         0           0.76         0           1         0           0         0.2           0         0.4           0         0.6           0         0.8           0         1           0.066         0.066           0.175         0.175           0.284         0.284           0.392         0.392				

<sup>\*</sup>Tab of device attached to topside copper

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# **Design Considerations** (Continued)

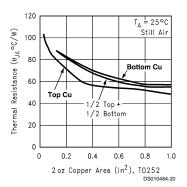


FIGURE 3.  $\theta_{\text{JA}}$  vs. 2oz Copper Area for TO-252

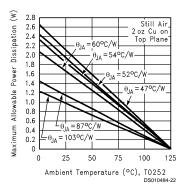


FIGURE 4. Maximum Allowable Power Dissipation vs. Ambient Temperature for TO-252

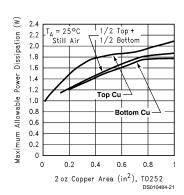
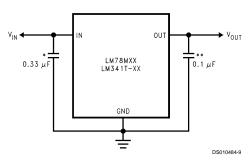
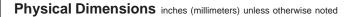


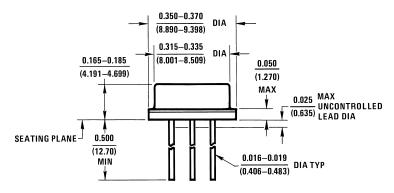
FIGURE 5. Maximum Allowable Power Dissipation vs. 2oz. Copper Area for TO-252

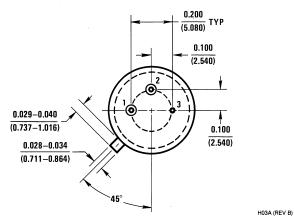
# **Typical Application**



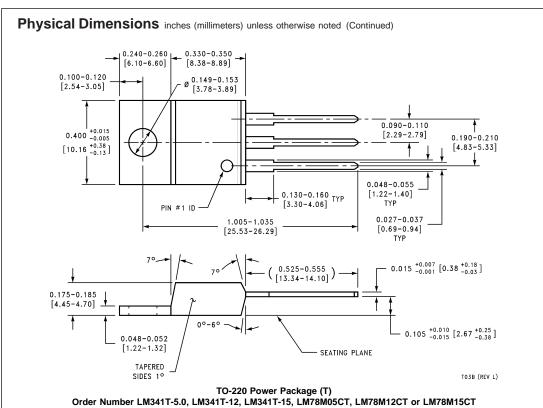
\*Required if regulator input is more than 4 inches from input filter capacitor (or if no input filter capacitor is used).
\*\*Optional for improved transient response.







TO-39 Metal Can Package (H) Order Number LM78M05CH, LM78M12CH or LM78M15CH NS Package Number H03A



NS Package Number T03B

## Physical Dimensions inches (millimeters) unless otherwise noted (Continued) 6.58±0.14 2.3±0.08 1.20±0.05 0.52±0.05 SEATING 4.32 MIN 6.10±0.1 PLANE 9.70±0.15 2.50 L <sub>0.83±0.1</sub> 0.52±0.05 **BACK VIEW**

DIMENSIONS ARE IN MILLIMETERS

TD03B (REV A)

TO-252 Order Number LM78M05CDT NS Package Number TD03B

0.17

1.0±0.1

### LIFE SUPPORT POLICY

3X 0.75±0.1

♦ 0.25 M A M B

4.57

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